

ABSTRACT

A plurality of lands and a plurality of conducting wires connected independently to each land are formed on one side surface of an insulating substrate of a flexible printed circuit board. Through-holes are formed through the
5 insulating substrate for exposing the lands to the other side surface. Solder is provided in the through-holes. The solder connects the lands to the head terminals on an inkjet head, which is located facing the other side surface of the
10 insulating substrate. The insulating substrate separates the solder from areas between the conducting wires and from areas between the lands, thereby preventing short circuits from occurring when manufacturing the connecting structure with a low tolerance grade.